



#### Specifications:

Applications : All high-density boards

Product Features : Small surface mountable, Solid state, Faster time to trip than standard SMD devices, Lower resistance

than standard SMD devices

Operation Current : 0.05A to 2.0A

Maximum Voltage : 6V to 60V

Temperature Range : -40°C to 85°C

#### Electrical Characteristics (23°C)

Hold	Trip	Rated	Maximum	Typical	Maximum Time to Trip		Resistance				
Current	Current	Voltage	Current	Power	Current	Time	R Minimum	R1 Maximum	Part Number		
I <sub>H</sub> , A	I <sub>T</sub> , A	V Maximum, V dc	I Maximum, A	Pd, W	Amp	Sec	ohms	ohms			
0.05	0.15	60			0.25	3.00	3.600	50.000	MC36203		
0.10	0.25	60	10	0.60	0.50	1.50	1.600	15.000	MC36205		
0.20	0.40	30				0.02	0.800	5.000	MC36208		
0.35	0.70	40			0.60	-	0.20	0.320	1.300	MC36212	
0.50	1.00	8	16	40	40			0.40	0.250	0.900	MC36214
0.75	1.50						0.10	0.130	0.400	MC36217	
1.10	2.20	6	100	0.80	8.00	0.30	0.060	0.210	MC36223		
1.50	3.00				0.80	-	0.50	0.040	0.110	MC36230	
1.75	4.00	6		0.8		0.60	0.020	0.080	MC36236		
2.00	4.00					1.00	0.015	0.070	MC36239		

I<sub>H</sub> = Hold current-maximum current at which the device will not trip at 23°C still air.

I<sub>T</sub> = Trip current-minimum current at which the device will always trip at 23°C still air.

V<sub>MAX</sub> = Maximum voltage device can withstand without damage at it rated current. (I maximum)

I<sub>MAX</sub> = Maximum fault current device can withstand without damage at rated voltage (V maximum).

Pd = Typical power dissipated-type amount of power dissipated by the device when in the tripped state in 23°C still air environment.

R<sub>MIN</sub> = Minimum device resistance at 23°C prior to tripping.

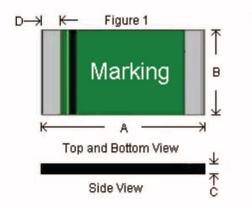
R1<sub>MAX</sub> = Maximum device resistance at 23°C measured 1 hour after tripping or reflow soldering of 260°C for 20 seconds.

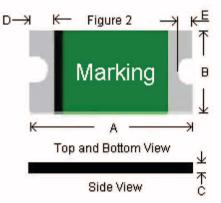
Termination pad characteristics Termination pad materials : Pure Tin





#### **Production Dimensions (Millimetre)**





#### Specifications Table

Figure	Α		В		С		D		E		Dord Number
		Maximum	Minimum	Maximum	Minimum	Maximum	Minimum	Maximum	Minimum	Maximum	Part Number
					0.00	1.15					MC36203
		2.42	0.05	35 2.80	0.60	1.15	0.05	0.75	5	-	MC36205
3.0	2.00				0.40	0.85					MC36208
						0.80					MC36212
					0.30	0.75					MC36214
	3.00	3.43	2.35		0.30	0.70	0.25				MC36217
2					0.60	1.00			0.10	0.45	MC36223
					0.50	0.90					MC36230
					0.80	1.40					MC36236
											MC36239

#### **Thermal Derating Curve**

# 200% 150% 150% 100% 50% -40 -20 0 20 40 60 80

Ambient Temperature (°C)

**Thermal Derating Curve** 

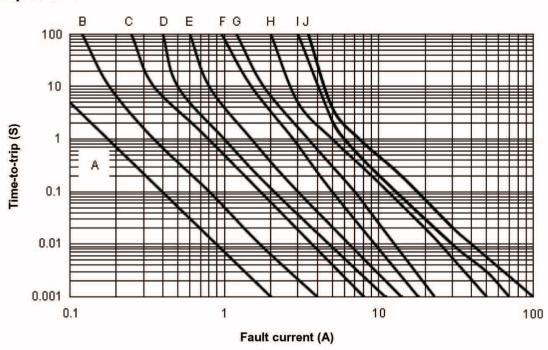
http://www.farnell.com http://www.newark.com http://www.cpc.co.uk



### surface Mountable PTC Resettable Fuses muttcomp

#### Typical Time-To-Trip at 23°C

A=MC36203 B=MC36205 C=MC36208 D=MC36212 E=MC36214 F=MC36217 G=MC36223 H=MC36230 I=MC36236 J=MC36239



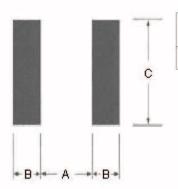
#### **Material Specification**

Terminal pad material : Pure Tir

Soldering characteristics : Meets EIA specification RS 186-9E, ANSI/J-std-002 Category 3

#### Pad Layouts, Solder Reflow and Rework Recommendations

The dimension in the table below provide the recommended pad layout for each FSMD1812 device



Device	A	B	C
	Nominal	Nominal	Nominal
All 0805 Series	1.20	1.00	1.50

**Dimensions: Millimetres** 





Average Ramp-Up Rate (Ts maximum to Tp) 3°C/second maximum  Preheat: Temperature Minimum (Ts minimum) 150°C	Profile Feature	Pb-Free Assembly
Temperature Minimum (Ts minimum) 150°C	Average Ramp-Up Rate (Ts maximum to Tp)	3°C/second maximum
Temperature Maximum (Ts maximum) 200°C Time (ts minimum to ts maximum) 60 to 180 seconds	Temperature Minimum (Ts minimum) Temperature Maximum (Ts maximum)	200°C

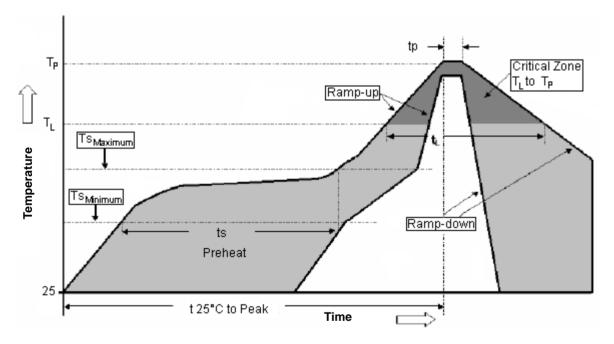
#### Solder reflow

Due to "Lead Free" nature, Temperature and Dwelling time for the soldering zone is higher than those for Regular. This may cause damage to other components.

- 1. Recommended max past thickness > 0.25mm.
- 2. Devices can be cleaned using standard methods and aqueous solvent.
- 3. Rework use standard industry practices.
- 4. Storage Envorinment : < 30°C/60% RH

#### Caution:

- 1. If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- 2. Devices are not designed to be wave soldered to the bottom side of the board.





#### **Part Number Table**

Description	Part Number
Surface Mountable PTC Resettable Fuse	MC36203
Surface Mountable PTC Resettable Fuse	MC36205
Surface Mountable PTC Resettable Fuse	MC36208
Surface Mountable PTC Resettable Fuse	MC36212
Surface Mountable PTC Resettable Fuse	MC36214
Surface Mountable PTC Resettable Fuse	MC36217
Surface Mountable PTC Resettable Fuse	MC36223
Surface Mountable PTC Resettable Fuse	MC36230
Surface Mountable PTC Resettable Fuse	MC36236
Surface Mountable PTC Resettable Fuse	MC36239

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